## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number   PMEG4010EXE-Q   Part Description   Nexperia DHAM   SMD package   Test Conditions Duration # Lots # Quantity # Rejects												
									TEST				,	
									Pre- and Post-Stress					
								# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
										JESD22-A113	.,			
										Bake Tamb = $125 ^{\circ}\text{C}$	24 hours			
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours											
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0								
	5	MIL-STD-750-1	•											
	HTRB	M1038 Method A												
		Tj = Tjmax, Vr = 100% of max. datasheet												
# B1	Bias	reverse voltage <sup>[1]</sup>	1000 hours	206	9320	0								
	тс	JESD22-A104												
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	311	14080	0								
	, , ,													
	UHAST	JESD22-A118												
# A3 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %												
		JESD22-A102	96 hours	311	14080	0								
	AC	Tamb = $121 ^{\circ}C$ , RH = $100 ^{\circ}M$												
# A3 alt	Autoclave	Pressure = $205 \text{ kPa} (29.7 \text{ psia})$												
	H3TRB	JESD22-A101												
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of												
# A2 alt	Temperature Reverse Bias		1000 hours	311	14080	0								
# A2 dit		MIL-STD-750 Method 1037	1000 110013	511	11000	0								
	IOL	ton = toff, devices powered to insure $\Delta T_j$ =												
# A5	Intermittent Operating Life		1000 hours	312	14120	0								
# AJ	inconnicient operating Life	100 C.0. 19000 Cycles	1000 110015	J12	11120	0								
	RSH	JESD22-A111												
# C8	Resistance to Solder Heat	$260 ^{\circ}\text{C} \pm 5 ^{\circ}\text{C}$	10 s	269	8070	0								
	SD	200 0 - 5 0	10.3	207	5570	5								
# C10	Solderability	J-STD-002		222	6660	0								
	,	des have to be considered (thermal runaway).		222	0000	U								

The physical limitations of Schottky diodes have to be considered (thermal runaway).
The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

confidence level of <i>n</i> , defated to 55°C, activation energy 0.7 eV, test time 100 to 1000 hours	nce level 60%, derated to 55 °C, activation energy 0.7 eV, t	test time 168 to 1000 nours
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Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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